

Silicon PIN Photodiode











DESCRIPTION

VBP104S and VBP104SR are high speed and high sensitive PIN photodiodes. It is a surface mount device (SMD) including the chip with a 4.4 mm² sensitive area detecting visible and near infrared radiation.

FEATURES

- Package type: surface mount
- · Package form: GW, RGW



- Radiant sensitive area (in mm2): 4.4
- · High photo sensitivity
- · High radiant sensitivity
- · Suitable for visible and near infrared radiation
- Fast response times
- Angle of half sensitivity: $\varphi = \pm 65^{\circ}$
- Floor life: 168 h, MSL 3, acc. J-STD-020
- · Lead (Pb)-free reflow soldering
- Compliant to RoHS Directive 2002/95/EC and in accordance to WEEE 2002/96/EC

APPLICATIONS

• High speed photo detector

PRODUCT SUMMARY				
COMPONENT I _{ra} (μA)		φ (deg)	λ _{0.1} (nm)	
VBP104S	35	± 65	430 to 1100	
VBP104SR	35	± 65	430 to 1100	

Note

· Test conditions see table "Basic Characteristics"

ORDERING INFORMATION					
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM		
VBP104S	Tape and reel	MOQ: 1000 pcs, 1000 pcs/reel	Gullwing		
VBP104SR	Tape and reel	MOQ: 1000 pcs, 1000 pcs/reel	Reverse gullwing		

Note

MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS (T _{amb} = 25 °C, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V _R	60	V
Power dissipation	T _{amb} ≤ 25 °C	P _V	215	mW
Junction temperature		Tj	100	°C
Operating temperature range		T _{amb}	- 40 to + 100	°C
Storage temperature range		T _{stg}	- 40 to + 100	°C
Soldering temperature	Acc. reflow solder profile fig. 8	T _{sd}	260	°C
Thermal resistance junction/ambient		R _{thJA}	350	K/W



PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	I _F = 50 mA	V _F		1	1.3	V
Breakdown voltage	I _R = 100 μA, E = 0	V _(BR)	60			V
Reverse dark current	V _R = 10 V, E = 0	I _{ro}		2	30	nA
Diode capacitance	V _R = 0 V, f = 1 MHz, E = 0	C _D		48		pF
	V _R = 3 V, f = 1 MHz, E = 0	C _D		17	40	pF
Open circuit voltage	$E_{e} = 1 \text{ mW/cm}^{2}, \lambda = 950 \text{ nm}$	Vo		350		mV
Temperature coefficient of Vo	$E_e = 1 \text{ mW/cm}^2, \lambda = 950 \text{ nm}$	TK _{Vo}		- 2.6		mV/K
Short circuit current	$E_e = 1 \text{ mW/cm}^2, \lambda = 950 \text{ nm}$	I _k		32		μΑ
Temperature coefficient of I _k	$E_{e} = 1 \text{ mW/cm}^{2}, \lambda = 950 \text{ nm}$	TK _{lk}		0.1		%/K
Reverse light current	$E_e = 1 \text{ mW/cm}^2, \lambda = 950 \text{ nm}, \\ V_R = 5 \text{ V}$	I _{ra}	25	35		μΑ
Angle of half sensitivity		φ		± 65		deg
Wavelength of peak sensitivity		λ_{p}		940		nm
Range of spectral bandwidth		λ _{0.1}		430 to 1100		nm
Noise equivalent power	$V_R = 10 \text{ V}, \ \lambda = 950 \text{ nm}$	NEP		4 x 10 ⁻¹⁴		W/√Hz
Rise time	V_R = 10 V, R_L = 1 k Ω , λ = 820 nm	t _r		100		ns
Fall time	V_R = 10 V, R_L = 1 kΩ, λ = 820 nm	t _f		100		ns

BASIC CHARACTERISTICS (Tamb = 25 °C, unless otherwise specified)

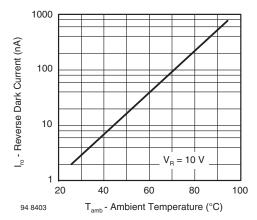


Fig. 1 - Reverse Dark Current vs. Ambient Temperature

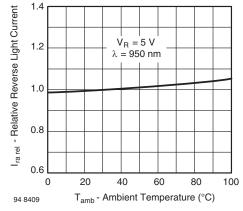


Fig. 2 - Relative Reverse Light Current vs. Ambient Temperature



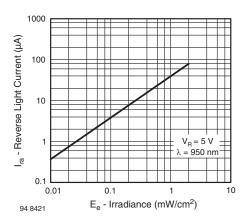


Fig. 3 - Reverse Light Current vs. Irradiance

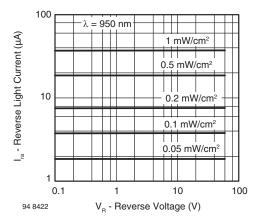


Fig. 4 - Reverse Light Current vs. Reverse Voltage

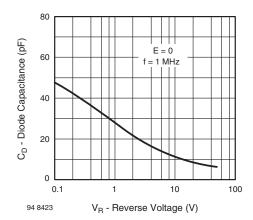


Fig. 5 - Diode Capacitance vs. Reverse Voltage

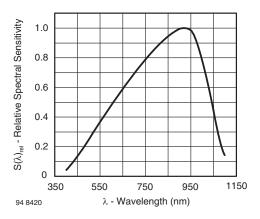


Fig. 6 - Relative Spectral Sensitivity vs. Wavelength

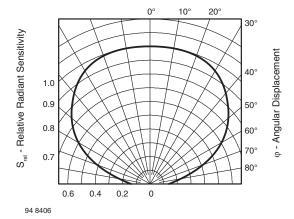
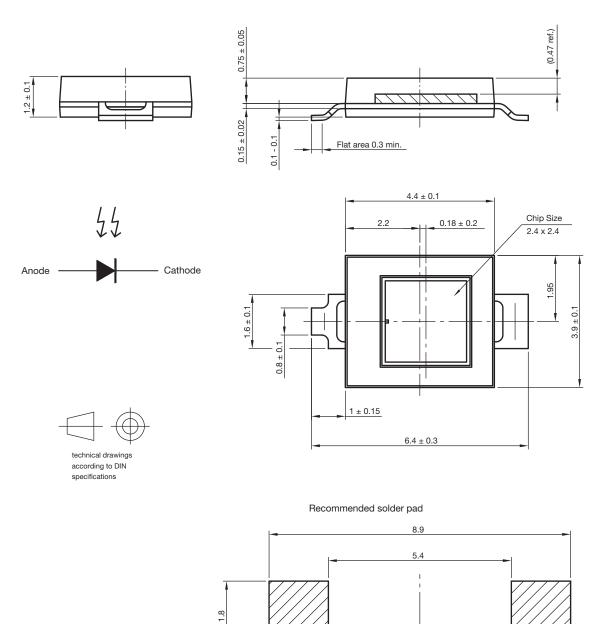


Fig. 7 - Relative Radiant Sensitivity vs. Angular Displacement

PACKAGE DIMENSIONS FOR VBP104S in millimeters

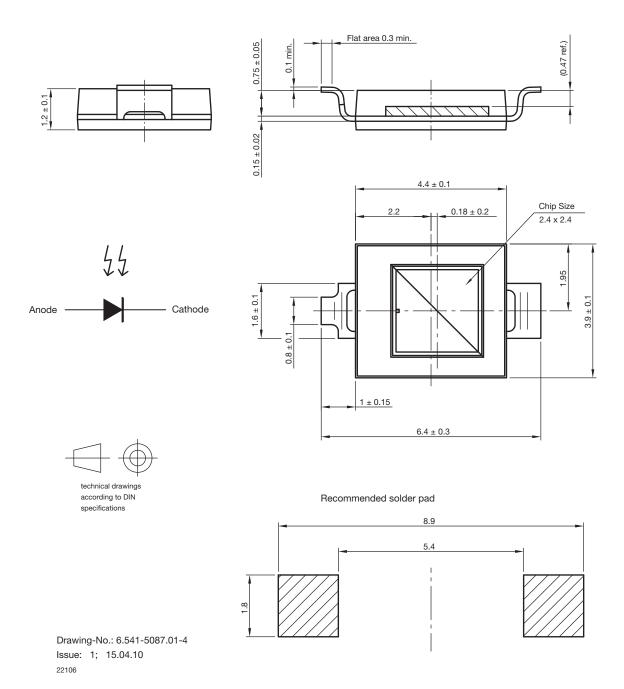


Drawing-No.: 6.541-5088.01-4

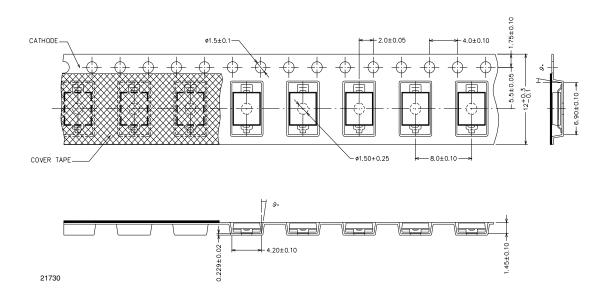
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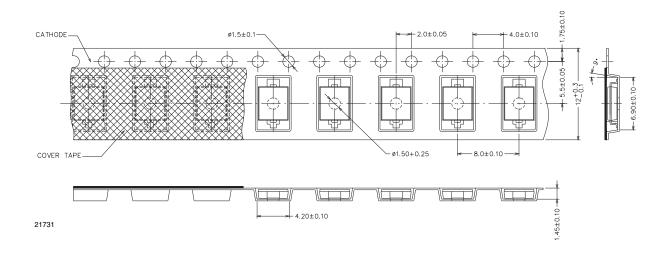
PACKAGE DIMENSIONS FOR VBP104SR in millimeters



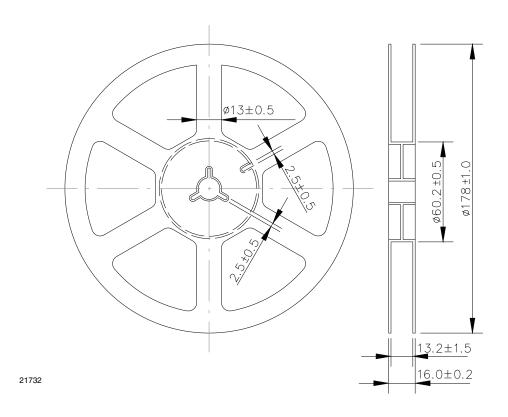
TAPING DIMENSIONS FOR VBP104S in millimeters



TAPING DIMENSIONS FOR VBP104SR in millimeters



REEL DIMENSIONS FOR VBP104S AND VBP104SR in millimeters



SOLDER PROFILE

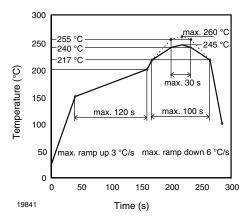


Fig. 8 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

FLOOR LIFE

Time between soldering and removing from MBB must not exceed the time indicated in J-STD-020:

Moisture sensitivity: level 3

Floor life: 168 h

Conditions: T_{amb} < 30 °C, RH < 60 %

DRYING

In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or recommended conditions:

192 h at 40 °C (+ 5 °C), RH < 5 %

or

96 h at 60 °C (+ 5 °C), RH < 5 %.





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